

Electronic Version

Stylesheet Version v1.1.1

[STRUCTURE OF FLIP CHIP PACKAGE WITH AREA BUMP]

Abstract

A structure of flip chip package with an area bump has at least a chip (also known as a die), a substrate, a plurality of first bumps (normal bumps) and at least a second bump (area bump), wherein the first bumps are electrically and mechanically connected to one of first bonding pads and the corresponding one of first contact pads. The second bump is electrically and mechanically connected to a second bonding pad and the corresponding second contact pad of the substrate, wherein the size of the second bump is larger than one of the first bumps. Because the size of the second bump is larger than one of the first bumps, the structure has much better electrical performance and performance of heat dissipation.